PCN# : P287A
Issue Date : Dec. 12, 2012

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

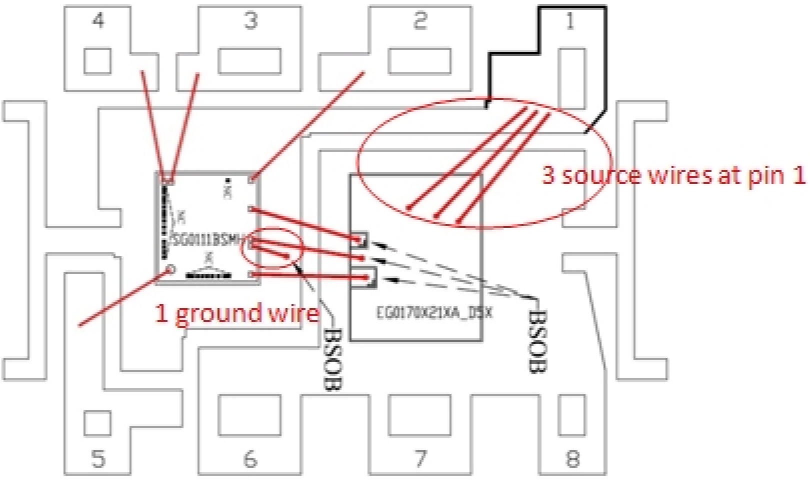
Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : Mar. 12, 2013

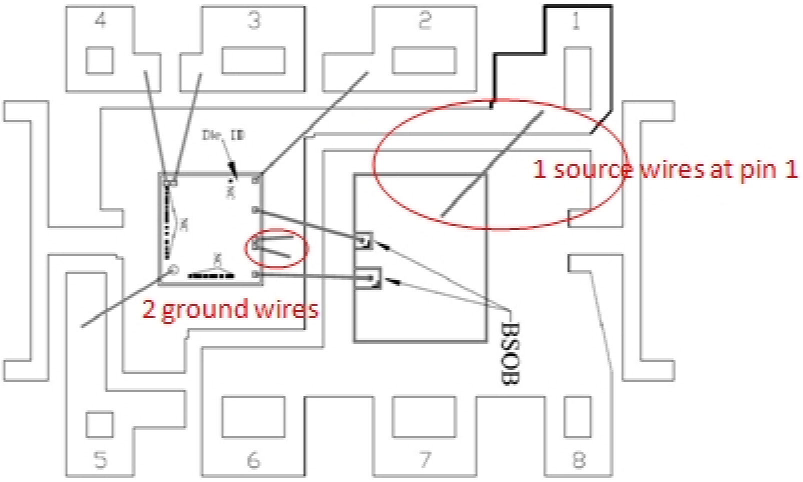
Expected First Date Code of Changed Product :1218

Description of Change (From) :
Current bond layout is having one ground wire and three sources wires at pin 1



Description of Change (To) :

New bond layout is having two ground wires and only one source wire at pin 1.
Note: No change to Bill of Materials (BOM), Package outline dimension (POD) and electrical characteristics of device.



Reason for Change:
To Improve assembly process &product robustness by adding additional ground bond.

Affected Product(s):

DNP013		

Qualification Plan	**Device**	**Package**	**Process**	**No. of Lots**
QP2012032A	DNP013	DIP8	MXIC Process H	1 for HTOL, 3 for TMCL

Test Description:	**Condition:**	**Standard :**	**Duration:**	**Results:**
High Temperature Operating Life Test	115C, VDD=22V;HV=560V;VD=560V	JESD22-A108	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	100, 500 cycles	0/231